P295, Metallized Impregnated Paper, Class Y1, 500 VAC



Overview

Multilayer metallized paper, encapsulated and impregnated in self-extinguishing material that meets the requirements of UL 94 V-0.

Automotive grade devices meet the demanding Automotive Electronics Council's AEC-Q200 qualification requirements.

Applications

Safety capacitors for bridging of double or reinforced insulation applications that require a voltage test up to 4,000 VAC at 60 seconds. P295 series capacitors can be left in place during this test.

Benefits

Approvals: ENEC, UL, cUL, CQC
Rated voltage: 500 VAC 50/60 Hz
Capacitance range: 470 - 4,700 pF

· Lead spacing: 15.0 mm

• Capacitance tolerance: ±20%

Climatic category: 40/115/56/B, IEC 60068-1

Tape and reel packaging in accordance with IEC 60286-2

· RoHS Compliant and lead-free terminations

Operating temperature range of -40°C to +115°C

 100% screening factory test at 4,000 VAC, 50 Hz, 2 seconds

Highest possible safety regarding active and passive flammability

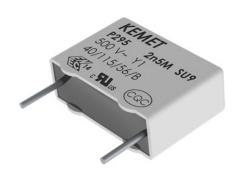
 Excellent self-healing properties ensure long life even when subjected to frequent over voltages

Good resistance to ionization due to impregnated dielectric

High dV/dt capability

 Impregnated paper provides excellent stability and reliability properties, particularly in applications with continuous operation

Automotive Grade (AEC-Q200)



Part Number System

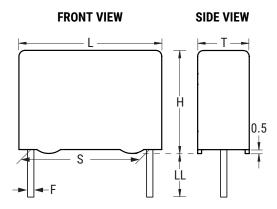
P	295	В	E	471	M	500	A
Capacitor Class	Series	Lead Spacing (mm)	Size Code	Capacitance Code (pF)	Capacitance Tolerance	Rated Voltage (VAC)	Packaging
P = Paper	Y1, Metallized Paper	B = 15.0	See Dimension Table	First two digits represent significant figures. Third digit specifies number of zeros.	J = ±5% K = ±10% M = ±20%	500 = 500	See Ordering Options Table



Ordering Options Table

Lead Spacing Nominal (mm)	Type of Leads and Packaging	Lead Length (mm)	KEMET Part Number (Insert at 14th character)
	Standard Lead and Packaging Options		
15	Bulk – Short Leads	6 +0/-1	С
15	Bulk – Maximum Length Leads	30 +5/-0	A
	Tape and Reel (Standard Reel Φ = 360 mm)	H ₀ = 18.5 +/-0.5	L

Dimensions - Millimeters



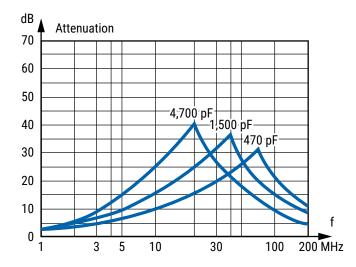
Size Code	S		<u> </u>				Н		L		F	
	Nominal	Tolerance	Nominal	Nominal Tolerance		Tolerance	Nominal	Tolerance	Nominal	Tolerance		
BE	15.0	±0.4	5.5	Maximum	12.5	Maximum	18.0	Maximum	0.8	±0.05		
BJ	15.0	±0.4	6.5	Maximum	12.5	Maximum	18.0	Maximum	0.8	±0.05		
BL	15.0	±0.4	7.5	Maximum	14.5	Maximum	18.0	Maximum	0.8	±0.05		
BQ	15.0	±0.4	8.5	Maximum	16.0	Maximum	18.0	Maximum	0.8	±0.05		
	Note: See Ordering Options Table for lead length (LL) options.											



Performance Characteristics

Rated Voltage	500 VAC 50/60 Hz				
Capacitance Range	0.00047 - 0.0047 μF				
Capacitance Tolerance	±20%				
Temperature Range	-40°C to +115°C				
Climatic Category	40/115/56/B				
Approvals	ENEC, UL, cUL, CQC				
D	Maximum Values at +23°C				
Dissipation Factor	1 kHz	1.3%			
Test Voltage Between Terminals	The 100% screening factory test 50 Hz, 2 seconds. The voltage le requirements in applicable equip characteristics are checked afte	evel is selected to meet the oment standards. All electrical			
	Measured at 500 VDC a	fter 60 seconds, +23°C			
Insulation Resistance	Minimum Value B	etween Terminals			
	≥ 12,000 MΩ				
In DC Applications	Recommended voltage ≤ 1,500 VDC				
Resonance Frequency	Tabulated self-resonance freque length	encies f ₀ refer to 5 mm lead			

Suppression vs. Frequency, Typical Values





Environmental Test Data

Test	IEC Publication	Procedure			
Endurance	IEC 60384-14	$1.7~{\rm x~V_R}$ VAC 50 Hz, once every hour increase to 1,000 VAC for 0.1 second, 1,000 hours at upper rated temperature			
Vibration	IEC 60068-2-6 Test Fc	3 directions at 2 hours each 10-500 Hz at 0.75 mm or 98m/second ²			
Bump	IEC 60068-2-29 Test Eb	4,000 bumps at 390 m/second ²			
Change of Temperature	IEC 60068-2-14 Test Na	Upper and lower rated temperature 5 cycles			
Passive Flammability	IEC 60384-14	IEC 60384-1, IEC 60695-11-5 Needle flame test			
Damp Heat Steady State	IEC 60068-2-78 Test Cab	+40°C and 93% RH, 56 days			

Approvals

Certification Body	Mark	Specification	File Number
Intertek Semko AB		EN/IEC 60384-14	SE/0140-34A
UL	c FL us	UL 60384-14 CAN/CSA-E60384-14-09	E73869
cqc	Cec	IEC 60384-14	CQC16001145222



Environmental Compliance

All KEMET EMI capacitors are RoHS compliant.



Table 1 – Ratings & Part Number Reference

Capacitance	Maximu	m Dimensior	ns in mm	Lead Spacing	f	dV/dt	KEMET
Value (µF)	Т	Н	L	(S)	(MHz)	(V/µs)	Part Number
0.00047	5.5	12.5	18.0	15.0	64	2,000	P295BE471(3)500(1)
0.00056	5.5	12.5	18.0	15.0	59	2,000	P295BE561(3)500(1)
0.00068	5.5	12.5	18.0	15.0	54	2,000	P295BE681(3)500(1)
0.00082	5.5	12.5	18.0	15.0	49	2,000	P295BE821(3)500(1)
0.001	5.5	12.5	18.0	15.0	46	2,000	P295BE102(2)500(1)
0.0012	6.5	12.5	18.0	15.0	43	2,000	P295BJ122(2)500(1)
0.0015	6.5	12.5	18.0	15.0	40	2,000	P295BJ152(2)500(1)
0.0018	6.5	12.5	18.0	15.0	37	2,000	P295BJ182(2)500(1)
0.0022	6.5	12.5	18.0	15.0	33	2,000	P295BJ222(2)500(1)
0.0025	7.5	14.5	18.0	15.0	31	2,000	P295BL252(2)500(1)
0.0027	7.5	14.5	18.0	15.0	30	2,000	P295BL272(2)500(1)
0.0033	7.5	14.5	18.0	15.0	27	2,000	P295BL332(2)500(1)
0.0039	8.5	16.0	18.0	15.0	24	2,000	P295BQ392(2)500(1)
0.0047	8.5	16.0	18.0	15.0	22	2,000	P295BQ472(2)500(1)
Capacitance Value (µF)	T (mm)	H (mm)	L (mm)	Lead Spacing (S)	f _。 (MHz)	dV/dt (V/µs)	KEMET Part Number

⁽¹⁾ Insert ordering code for lead type and packaging. See Ordering Options Table for available options.

⁽²⁾ Insert tolerance letter ($J = \pm 5\%$, $K = \pm 10\%$, $M \pm 20\%$)

⁽³⁾ Insert tolerance letter ($K = \pm 10\%$, $M \pm 20\%$)



Soldering Process

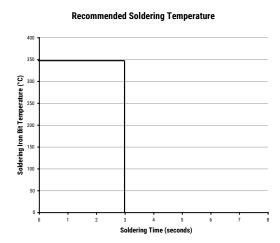
The implementation of the RoHS directive has resulted in the selection of SnAuCu (SAC) alloys or SnCu alloys as primary solder. This has increased the liquidus temperature from 183°C for SnPb eutectic alloys to 217 – 221°C for the new alloys. As a result, the heat stress to the components, even in wave soldering, has increased considerably due to higher pre-heat and wave temperatures. Polypropylene capacitors are especially sensitive to heat (the melting point of polypropylene is 160 – 170°C). Wave soldering can be destructive, especially for mechanically small polypropylene capacitors (with lead spacing of 5 mm to 15 mm), and great care must be taken during soldering. The recommended solder profiles from KEMET should be used. Consult KEMET with any questions. In general, the wave soldering curve from IEC Publication 61760-1 Edition 2 serves as a solid guideline for successful soldering. See Figure 1.

Reflow soldering is not recommended for through-hole film capacitors. Exposing capacitors to a soldering profile in excess of the recommended limits may result in degradation of or permanent damage to the capacitors.

Do not place the polypropylene capacitor through an adhesive curing oven to cure resin for surface mount components. Insert through-hole parts after the curing of surface mount parts. Consult KEMET to discuss the actual temperature profile in the oven, if through-hole components must pass through the adhesive curing process. A maximum of two soldering cycles is recommended. Allow time for the capacitor surface temperature to return to normal before the second soldering cycle.

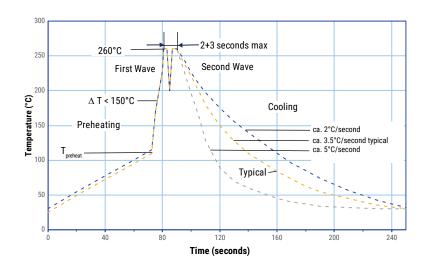
Manual Soldering Recommendations

Following is the recommendation for manual soldering with a soldering iron.



The soldering iron tip temperature should be set at 350°C (+10°C maximum) with the soldering duration not to exceed more than 3 seconds.

Wave Soldering Recommendations





Soldering Process cont.

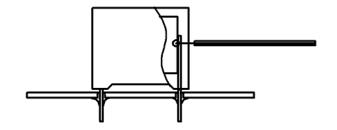
Wave Soldering Recommendations cont.

1. The table indicates the maximum set-up temperature of the soldering process.

Dielectric film material	Maximun Tempe	n Preheat erature	Maximum Peak Soldering Temperature			
	Capacitor Pitch ≤ 15 mm	Capacitor Pitch > 15 mm	Capacitor Pitch ≤ 15 mm	Capacitor Pitch > 15 mm		
Polyester	130°C	130°C	270°C	270°C		
Polypropylene	110°C	130°C	260°C	270°C		
Paper	130°C	140°C	270°C	270°C		
Polyphenylene Sulphide	150°C	160°C	270°C	270°C		

2. The maximum temperature measured inside the capacitor. Set the temperature so that inside the element the maximum temperature is below the limit:

Dielectric Film Material	Maximum temperature measured inside the element
Polyester	160°C
Polypropylene	110°C
Paper	160°C
Polyphenylene Sulphide	160°C



Temperature monitored inside the capacitor.

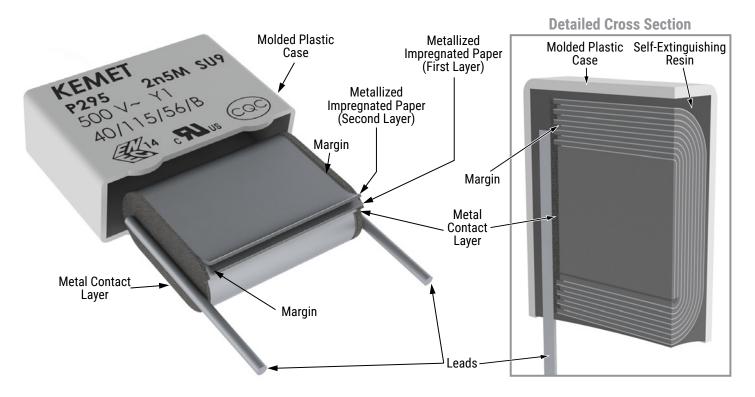
Selective Soldering Recommendations

Selective dip soldering is a variation of reflow soldering. In this method, the printed circuit board with through-hole components to be soldered is preheated and transported over the solder bath, as in normal flow soldering, without touching the solder. When the board is over the bath, it is stopped. Pre-designed solder pots are lifted from the bath with molten solder only at the places of the selected components, and then pressed against the lower surface of the board to solder the components.

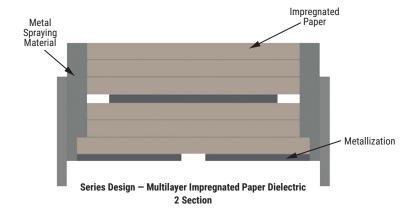
The temperature profile for selective soldering is similar to the double-wave flow soldering outlined in this document. **However, instead of two baths, there is only one with a time from 3 to 10 seconds.** In selective soldering, the risk of overheating is greater than in double-wave flow soldering, and great care must be taken so that the parts do not overheat.



Construction

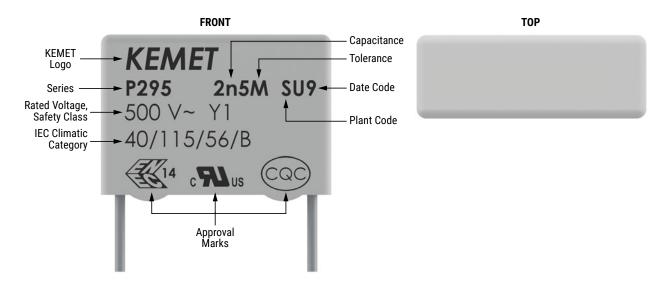


Winding Scheme





Marking



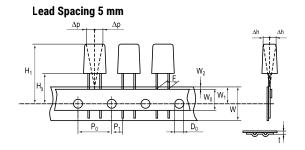
	Manufacturing Date Code (IEC 60062)											
Year Code Year Code Month Code Month (
2020	М	2027	V	2034	E	January	1	July	7			
2021	N	2028	W	2035	F	February	2	August	8			
2022	Р	2029	X	2036	Н	March	3	September	9			
2023	R	2030	Α	2037	J	April	4	October	0			
2024	S	2031	В	2038	K	May	5	November	N			
2025	Т	2032	С	2039	L	June	6	December	D			
2026	U	2033	D	2040	М							

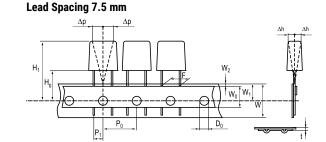
Packaging Quantities

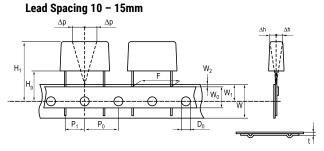
Lead Spacing (mm)	Thickness (mm)	Height (mm)				Bulk Long Leads	Standard Reel 360 mm
L	ead and Packag	ing Code		С	Α	L	
	5.5	12.5	18	1,000	500	600	
15	7.5		18	600	400	400	
15	6.5	12.5	18	600	400	400	
	8.5	16	18	400	250	400	

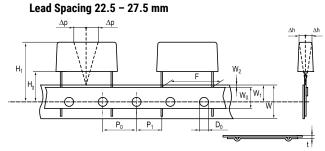


Lead Taping & Packaging (IEC 60286-2)

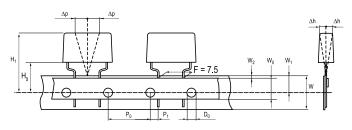








Formed Leads from 10 and 15 mm to 7.5 mm



Taping Specification

Dimensions in mm										
Lead Spacing	+0.6/-0.1	F	5	7.5	Formed 7.5	10	15	22.5	27.5	F
Carrier Tape Width	±0.5	W	18	18	18	18	18	18	18	18+1/-0.5
Hold-down Tape Width	Minimum	W _o	5	5	5	5	5	5	5	
Position of Sprocket Hole	±0.5	W ₁	9	9	9	9	9	9	9	9+0.75/-0.5
Distance Between Tapes	Maximum	W ₂	3	3	3	3	3	3	3	3
Sprocket Hole Diameter	±0.2	D ₀	4	4	4	4	4	4	4	4
Feed Hole Lead Spacing	±0.3	P ₀ (1)	12.7	12.7	12.7 (4)	12.7	12.7	12.7	12.7	12.7
Distance Lead - Feed Hole	±0.7	P ₁	3.85	3.75	3.75	7.7	5.2	5.3	5.3	P1
Deviation Tape - Plane	Maximum	Δр	1.3	1.3	1.3	1.3	1.3	1.3	1.3	1.3
Lateral Deviation	Maximum	Δh	2	2	2	2	2	2	2	2
Total Thickness	±0.2	t	0.7	0.7	0.7	0.7	0.7	0.9 Maximum	0.9 Maximum	0.9 Maximum
Sprocket Hole/Cap Body	Nominal	H ₀ (2)	18.5±0.5	18.5±0.5	18.5±0.5	18.5±0.5	18.5±0.5	18.5±0.5	18.5±0.5	18.0+2/-0
Sprocket Hole/ Top of Cap Body	Maximum	H ₁ (3)	32	31	43	43	43	58	58	58 Maximum

⁽¹⁾ Maximum cumulative feed hole error, 1 mm per 20 parts

^{(2) 16.5} mm available on request

⁽³⁾ Depending on case size

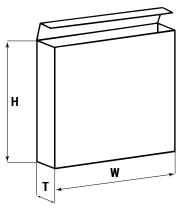
^{(4) 15} mm available on request



Lead Taping & Packaging (IEC 60286-2) cont.

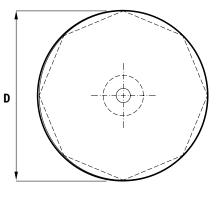
Ammo Specifications

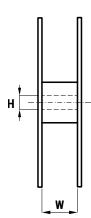
Series	Dimensions (mm)		
	Н	W	Т
P295	330	330	50



Reel Specifications

Series	Dimensions (mm)		
	D	Н	W
P295	360 500	30	46 (Max)







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